Filed: April 26, 2000

For: METHOD AND COMPOSITION FOR SELECTIVELY ETCHING AGAINST COBALT SILICIDE

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- 39. (Once Amended) The composition according to claim 38, wherein the ratio is in a range of about 1:1:25 (mineral acid:peroxide:deionized water) to about 1:1:10 (mineral acid:peroxide:deionized water).
- 46. (New) The composition according to claim 38, wherein the mineral acid is selected from a group consisting of HCl, HNO₃, H₂SO₄, H₃PO₄, and HF.
- 47. (New) An etching composition, the composition comprising a mineral acid, a peroxide, and deionized water at a ratio in a range of about 1:1:35 (mineral acid:peroxide:deionized water) to about 1:1:5 (mineral acid:peroxide:deionized water), wherein the composition has an etch rate greater than about 1000 Å/minute for cobalt.

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- 48. (New) The etching composition according to claim 47, wherein the mineral acid is HCl.
- 49. **(New)** The etching composition according to claim 47, wherein the peroxide is hydrogen peroxide.
- 50. (New) The composition according to claim 47, wherein the ratio is in a range of about 1:1:25 (mineral acid:peroxide:deionized water) to about 1:1:10 (mineral acid:peroxide:deionized water).
- 51. (New) The composition according to claim 47, wherein the composition has an etch rate of about 50 Å/minute to about 250 Å/minute for metal nitride.
- 52. (New) An etching composition, the composition comprising a mineral acid, a peroxide, and deionized water at a ratio in a range of about 1:1:35 (mineral acid:peroxide:deionized water) to about 1:1:5 (mineral acid:peroxide:deionized water), wherein the composition has an etch rate of about 50 Å/minute to about 250 Å/minute for metal nitride.

- 53. (New) The etching composition according to claim 52, wherein the mineral acid is HCl.
- 54. (New) The etching composition according to claim 52, wherein the peroxide is hydrogen peroxide.
- 55. (New) The composition according to claim 52, wherein the ratio is in a range of about 1:1:25 (mineral acid:peroxide:deionized water) to about 1:1:10 (mineral acid:peroxide:deionized water).
- 56. (New) An etching composition, the composition consisting essentially of a mineral acid, a peroxide, and deionized water.
- 757. (New) The composition according to claim 56, wherein the mineral acid is HCl and the peroxide is hydrogen peroxide.
- 7 78. (New) The composition according to claim 57, wherein the composition comprises a ratio in a range of about 1:1:35 (mineral acid:peroxide:deionized water) to about 1:1:5 (mineral acid:peroxide:deionized water).
- (New) The composition according to claim 58, wherein the ratio is in a range of about 1:1:25 (mineral acid:peroxide:deionized water) to about 1:1:10 (mineral acid:peroxide:deionized water).
- 60. (New) The composition according to claim 56, wherein the mineral acid is selected from a group consisting of HCl, HNO, H₂SO₄, H₃PO₄, and HF.

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